



End of Life Notification

Tflex HR400 - Thermal Interface Material

June 1st, 2024

Dear Laird Valued Customer:

This letter is to inform you that Laird™ Tflex HR400 Gap filler material will be transitioning through an end of life (EOL) process. The primary reasons for implementing EOL is diminishing demand. We wish to alert you that the final buy date to submit a purchase order for this product will be December 3rd, 2024. Laird's final ship date will be May 30th, 2025.

Laird has many other gap filler materials that can replace Tflex HR400 in your application. Some options may include Tflex 300 (1.2 W/mk) or Tflex B200 (2 W/mk), comparison shown below.

Typical Property	Tflex 300	Tflex HR400	Tflex B200
Thermal Conductivity (W/mk)	1.2	1.8	2.0
Density (g/cc)	1.8	1.9	2.2
Hardness (Shore 00, 3 sec)	25	53	42
Outgassing TML (%)	0.56	0.32	0.28
Outgassing CVCM (%)	0.10	0.09	0.07
Rth@ 40 mils, 10 psi	0.98°C-in ² /W	1.00°C-in ² /W	1.10°C-in ² /W

We thank you for your continued business and support. If you have any questions, please contact the Laird Performance Materials sales representative in your region.

Erin Swanbeck

Product Manager - Thermal
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